

Packaging Japan TC Chapter Meeting Summary and Minutes

SEMI Japan Standards Spring 2014 Meetings
Thursday, July 14, 2014, 15:00-17:00
SEMI Japan, Tokyo, Japan

Next Committee Meeting

SEMI Japan Standards Summer 2014 Meetings
Monday, September 29, 2014, 15:00-17:00
SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Kazunori Kato (AiT), Yutaka Koma (Consultant), Masahiro Tsuruya (iNEMI)

SEMI Staff: Naoko Tejima (SEMI Japan)

| <i>Company</i> | <i>Last</i> | <i>First</i> | <i>Company</i> | <i>Last</i> | <i>First</i> |
|-----------------------|-------------|--------------|---------------------|-------------|--------------|
| Tokyo Seimitsu | Chiba | Kiyotaka | Toray Engineering | Nishimura | Koji |
| Fujitsu Semiconductor | Hayasaka | Noboru | AIST | Shimamoto | Haruo |
| AIST | Kada | Morihiro | Micron Memory Japan | Sonobe | Kaoru |
| AiT | Kato | Kazunori | Asahi Glass | Takahashi | Shintaro |
| Shin-Etsu Polymer | Maekawa | Mitsunori | iNEMI | Tsuruya | Masahiro |
| Disco | Masuchi | Sumio | Lintec | Watanabe | Kenichi |
| Lintec | Murakami | Yukinori | SEMI Japan | Tejima | Naoko |
| Consultant | Nakamura | Kazuhiko | | | |

** alphabetical order by last name*

Table 2 Leadership Changes

None.

Table 3 Ballot Results

None.

Table 4 Authorized Ballots

| # | When | SC/TF/WG | Details |
|------|-------|------------------------------------|---|
| 5753 | C5-14 | Packaging 5 Year Review Task Force | Reapproval of SEMI G74-0699 (Reapproved 0706) - Specification for Tape Frame for 300 mm Wafers |
| 5754 | C5-14 | Packaging 5 Year Review Task Force | Reapproval of SEMI G77-0699 (Reapproved 0706) - Specification for Frame Cassette for 300 mm Wafers |
| 5755 | C5-14 | Packaging 5 Year Review Task Force | Reapproval of SEMI G81-0307 Specification for Map Data Items |
| 5756 | C5-14 | Packaging 5 Year Review Task Force | Reapproval of SEMI G81.1-0307 - Specification of Grand Concept of Map Data for Characteristics of Dice on Substrate |
| 5757 | C5-14 | Packaging 5 Year Review Task Force | Reapproval of SEMI G87-1108 Specification for Plastic Tape Frame for 300 mm Wafer |

Table 5 Authorized Activities

| # | Type | SC/TF/WG | Details |
|------|-------|------------------------------------|---|
| 5753 | SNARF | Packaging 5 Year Review Task Force | Reapproval of SEMI G74-0699 (Reapproved 0706) - Specification for Tape Frame for 300 mm Wafers |
| 5754 | SNARF | Packaging 5 Year Review Task Force | Reapproval of SEMI G77-0699 (Reapproved 0706) - Specification for Frame Cassette for 300 mm Wafers |
| 5755 | SNARF | Packaging 5 Year Review Task Force | Reapproval of SEMI G81-0307 Specification for Map Data Items |
| 5756 | SNARF | Packaging 5 Year Review Task Force | Reapproval of SEMI G81.1-0307 - Specification of Grand Concept of Map Data for Characteristics of Dice on Substrate |
| 5757 | SNARF | Packaging 5 Year Review Task Force | Reapproval of SEMI G87-1108 Specification for Plastic Tape Frame for 300 mm Wafer |

Table 6 New Action Items (or move to Section 8, Action Item Review)

| Item # | Assigned to | Details |
|-------------|-----------------------|--|
| PKG140508-3 | Masahiro Tsuruya | To draft the consensus opinion of JA PKG Committee to the organization corresponding to the NA 3DS-IC Committee. |
| PKG140508-4 | Thin Chip Handling TF | To prepare SNARF and submit it at the next JA TC Chapter Meeting. |
| PKG140714-1 | SEMI staff | To prepare SNARF for SEMI G81, G81.1, G74, G77 and G87 Reapproval ballot and submit them for Cycle 5, 2014. |
| PKG140714-2 | SEMI staff | To submit the revised committee charter to co-chairs of JRSC. |
| PKG140714-3 | Kazunori Kato | To report the revised committee charter at JRSC. |

1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on May 8, 2014.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Kaoru Sonobe (Micron Memory Japan) / Kazunori Kato (AiT)

Discussion: None

Vote: 13 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_PKG_Previous_Mtg_Minutes_140714

4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2014 Calendar of Events, Global Standards Meeting Schedule, 2014 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, A&R Ballot Review, Change of SEMI Japan President and Contact Information.

Attachment: 02_SEMI_Staff_Report_140714

5 Liaison Reports

5.1 North America 3DS-IC Committee Report

No report was provided.

5.2 Taiwan 3DS-IC Committee Report

No report was provided.

6 Task Force Reports

6.1 Global Coordinating Subcommittee (GCS)

Kazunori Kato reported for the Global Coordinating Subcommittee (GCS) that there were no activities between the previous committee meeting and today.

6.2 Electromagnetic Characterization Study Group

No report was provided by the Task Force.

6.3 DFM Study Group

No report was provided by the Task Force.

6.4 450mm Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported for 450mm Japan Assembly & Test Die Preparation Task Force. The Task Force meeting was held in June 9. Of note:

- The activities of SEMI G88, G92 and G95 were almost settled.
- Handling of "G82-0301 Provisional Specification for 300mm Load Port for Frame Cassettes in Backend Process" was discussed. As the result, at first, the reapproval ballot will be submitted and if it failed, it should be changed to inactive status.
 - Q. Can the "provisional" document be changed to "inactive" status as "provisional" is?
 - A. Yes, it can.
- Regarding 450mm Notchless Wafer, activities will be continued to exchange information. The next International PI&C 450 mm TF (Leader: Shoji Komatsu, Acteon) will be held in October or November.

Attachment: 03_ATDP_TF_Report_140714

6.5 Fiducial Mark Interoperability Task Force

Sumio Masuchi reported for the Fiducial Mark Interoperability Task Force. There were no particular progress should be reported since the previous committee meeting. The debrief meeting of SEMICON West will be held soon.

Attachment: 04_Fiducial_Mark_Interoperability_TF_Report_140714

6.6 Thin Die Bending Strength Measurement Method Task Force

Haruo Shimamoto reported on progress for the Thin Chip Die Bending Strength Measurement Method Task Force. Of note:

- *Doc.#5691, New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending*, passed A&R in June. It will be published in July or August.
- TF is wrapping up the activities with additional experiments

6.7 Thin Chip Handling Task Force

Kazuhiko Nakamura reported on progress for the Thin Chip Handling Task Force. The Task Force met earlier in the day. Of note:

- Working for the document about measurement method of adhesive strength of tray and chip.
- Preliminary experiment will be made to finish the 1st draft in October.

6.8 5-Year-Review Task Force

Masahiro Tsuruya reported for the 5-Year-Review Task Force.

Motion: To submit SEMI G74-0699 Reapproval ballot for Cycle 5, 2014.

By / 2nd: Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Motion: To submit SEMI G77-0699 Reapproval ballot for Cycle 5, 2014.

By / 2nd: Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Motion: To submit SEMI G81-0307 Reapproval ballot for Cycle 5, 2014.

By / 2nd: Noboru Hayasaka (Fujitsu Semiconductor) / Masahiro Tsuruya (iNEMI)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Motion: To submit SEMI G81.1-0307 Reapproval ballot for Cycle 5, 2014.

By / 2nd: Noboru Hayasaka (Fujitsu Semiconductor) / Masahiro Tsuruya (iNEMI)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Motion: To submit SEMI G87-1108 Reapproval ballot for Cycle 5, 2014.

By / 2nd: Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

Discussion: None.

Vote: 13 in favor and 0 opposed. **Motion passed.**

Action Item: SEMI staff to prepare SNARF for SEMI G81, G81.1, G74, G77 and G87 Reapproval ballot and submit them for Cycle 5, 2014.

Attachment: 05_SNARF_of_SEMI-G74_140714

Attachment: 06_SNARF_of_SEMI-G77_140714

Attachment: 07_PKG 5year_Review_TF_Report_140714

Attachment: 08_SNARF_of_SEMI-G81_140714

Attachment: 09_SNARF_of_SEMI-G81.1_140714

Attachment: 10_SNARF_of_SEMI-G87_140714

6.9 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group.

Attachment: 11_3D-IC_SG_Report_140714

7 Old Business

7.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

| <i>Item #</i> | <i>Assigned to</i> | <i>Details</i> |
|---------------|-----------------------|--|
| PKG140508-1 | SEMI Staff | To forward adjudication result of Doc.#5691 to the ISC A&R Subcommittee for procedural review. Close |
| PKG140508-2 | Masahiro Tsuruya | To draft the PKG Committee Charter, modifying the description of EHS and 3D-IC. Close |
| PKG140508-3 | Masahiro Tsuruya | To draft the consensus opinion of JA PKG Committee to the organization corresponding to the NA 3DS-IC Committee. Open |
| PKG140508-4 | Thin Chip Handling TF | To prepare SNARF and submit it at the next JA TC Chapter Meeting. Open |

8 New Business

8.1 Event during SEMICON Japan 2014

3D-IC SG will be held on December 3 PM.

8.2 Packaging Committee Charter

Masahiro Tsuruya proposed the revised committee charter and was reviewed.

Motion: To approve the revised PKG Committee Charter.
By / 2nd: Masahiro Tsuruya (iNEMI) / Kazuhiko Nakamura (Consultant)
Discussion: None.
Vote: 13 in favor and 0 opposed. **Motion passed.**

Attachment: 12_PKG_Committee_Charter_140714

Action Item: SEMI staff to submit the revised committee charter to co-chairs of JRSC.

Action Item: Kazunori Kato to report the revised committee charter at JRSC.

9 Action Item Review

9.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

10 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Monday, September 29, 2014, 15:00-17:00, at SEMI Japan, Tokyo, Japan.



Respectfully submitted by:
Naoko Tejima
Manager, Standards
SEMI Japan
Phone: +81.3.3222.5804
Email: ntejima@semi.org

Minutes approved by:

| | |
|------------------------------------|--------------|
| Kazunori Kato (AiT), Co-chair | *** **, 2014 |
| Masahiro Tsuruya (iNEMI), Co-chair | *** **, 2014 |

Table 8 Index of Available Attachments #1

| # | <i>Title</i> |
|----|---|
| 1 | JA_PKG_Previous_Mtg_Minutes_140714 |
| 2 | SEMI_Staff_Report_140714 |
| 3 | ATDP_TF_Report_140714 |
| 4 | Fiducial_Mark_Interoperability_TF_Report_140714 |
| 5 | PKG_5year_Review_TF_Report_140714 |
| 6 | SNARF_of_SEMI-G74_140714 |
| 7 | SNARF_of_SEMI-G77_140714 |
| 8 | SNARF_of_SEMI-G81_140714 |
| 9 | SNARF_of_SEMI-G81.1_140714 |
| 10 | SNARF_of_SEMI-G87_140714 |
| 11 | 3D-IC_SG_Report_140714 |
| 12 | PKG_Committee_Charter_140714 |

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.